

GR 97 P 1903



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By: [Signature]

Date: January 24, 2002

FEB 23 2002

3-5-02
Malini

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hansjörg Reichert et al.

Applic. No. : 09/483,737

Filed : January 14, 2000

Title : Method and Apparatus for Producing a Chip-Substrate Connection

Examiner : Ahmed N. Sefer

Group Art Unit : 2826

A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

Sir:

Responsive to the Office action dated October 24, 2001 kindly amend the above-identified application as follows:

In the Claims:

Cancel claims 11-14 and 16.

A1 Claim 15 (amended). A semiconductor component, comprising:

Sub
B